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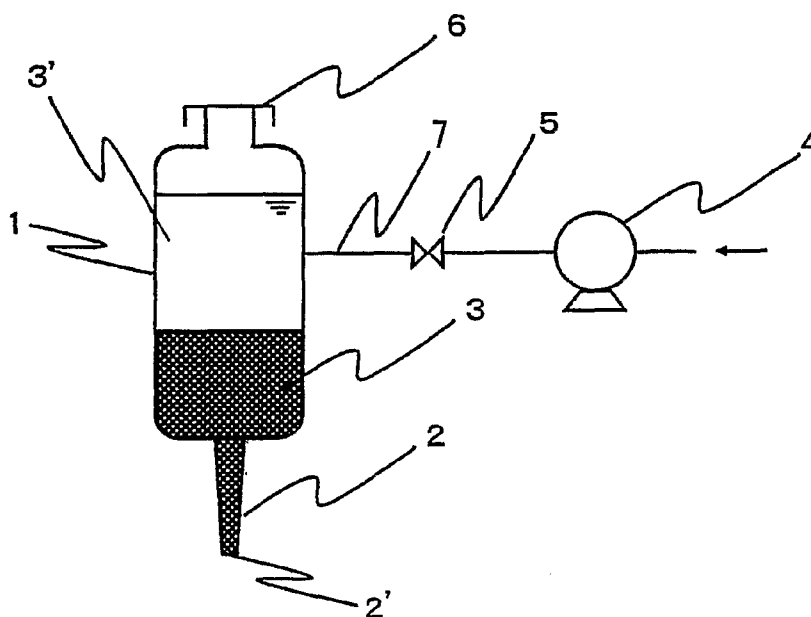
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(54) Title: METHOD FOR FORMING SOLDER LAYER ON PRINTED-WIRING BOARD AND SLURRY DISCHARGE DE-
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(57) Abstract: A method for forming a solder layer on the surface of a conductive circuit on a printed-wiring board includes discharging slurry containing solder powder onto the surface and heating the substrate. The slurry is discharged by dint of the pressure in a tank for the slurry. In a discharging device to be used in the method, the tank for storing the slurry is provided with a discharge pipe (2) for the slurry and a delivery pipe (1) for gas or solvent to be used for adjusting the pressure in the tank. In this device, one common pipe may be used both for discharging the slurry from the tank and delivering the slurry to the tank and one common pipe may be used for both delivering gas into the tank and sucking the gas from the tank.

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